



#### **General Description**

The MAX8563/MAX8564 ultra-low-output dual and triple LDO controllers allow flexible and inexpensive point-ofload voltage conversion in motherboards, desknotes, notebooks, and other applications.

Both parts feature a 0.5V reference voltage with ±1% accuracy providing tight regulation of the output voltage. The MAX8563 has three n-channel MOSFET controller outputs, and the MAX8564 has two controller outputs.

Each controller output is adjustable from 0.5V to 3.3V when VDD = 12V and between 0.5V and 1.8V when VDD = 5V. Each output is independently enabled and asserts a POK signal when the output reaches 94% of the set value. Each output is protected against a soft short-circuit condition by an undervoltage comparator that disables the output when it drops to under 80% of the set voltage for more than 50µs. For a catastrophic short condition, the regulators are shut down immediately if the output drops below 60% of the set voltage.

The MAX8563 is available in a 16-pin QSOP package, and the MAX8564 is available in a 10-pin µMAX® package.

#### **Applications**

Motherboards

**Dual/Triple Power Supplies** 

Desknotes and Notebooks

Graphic Cards

Ultra-Low-Dropout Voltage Regulators

Low-Voltage DSP, µP, and Microcontroller Power Supplies

### Features

♦ MAX8563: 3 Outputs ♦ MAX8564: 2 Outputs

- ♦ ±1% Feedback Regulation
- ♦ Adjustable Output Voltage Down to 0.5V
- **♦** Can Use Ceramic Output Capacitors
- ♦ Wide Supply Voltage Range Permits Operation from 5V or 12V Rails
- ♦ Individual Enable Control and POK Signal Allows Sequencing
- Overload Protection Against Soft-Short Condition
- ♦ Undervoltage Short-Circuit Protection
- ♦ Drive n-Channel MOSFETs

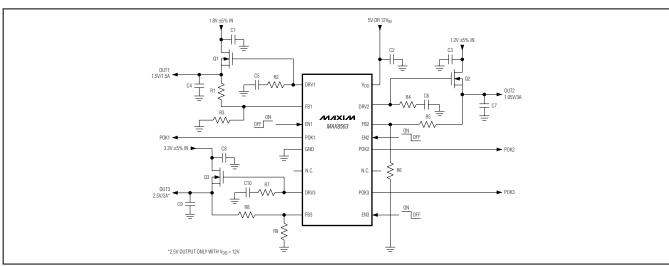
#### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE	
MAX8563EEE	-40°C to +85°C	16 QSOP	
MAX8564EUB	-40°C to +85°C	10 μMAX	

Pin Configurations appear at end of data sheet.

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### **Typical Operating Circuit**



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Maxim Integrated Products 1

#### **ABSOLUTE MAXIMUM RATINGS**

$\label{eq:vdp} \begin{array}{llllllllllllllllllllllllllllllllllll$	Operating Temperature Range40°C to +85°C Junction Temperature+150°C Storage Temperature Range65°C to +150°C Lead Temperature (soldering, 10s)+300°C
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Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

(VDD = VEN1 = VEN2 = VEN3 = 5V, VGND = 0V, TA = -40°C to +85°C, unless otherwise noted. Typical values are at TA = +25°C.) (Note 1)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS	
GENERAL			•				
V <sub>DD</sub> Voltage Range					13.2	V	
V <sub>DD</sub> Undervoltage-Lockout Threshold	Rising, 200mV hy	ysteresis (typ)	3.56	3.76	4.00	V	
V Ouissesst Current	$V_{EN} = V_{DD} = 12$	2V (MAX8563)		930	1600	μА	
V <sub>DD</sub> Quiescent Current	$V_{EN} = V_{DD} = 12$	2V (MAX8564)		660	1200		
V <sub>DD</sub> Shutdown Current	EN1 = EN2 = EN	3 = GND, V <sub>DD</sub> = 12V			25	μΑ	
LDOs							
ED Acquirecy	$T_A = 0^{\circ}C \text{ to } +85^{\circ}$	C	0.494	0.5	0.504	V	
FB_ Accuracy	$T_A = -40^{\circ}C \text{ to } +8$	5°C	0.489		0.509		
ED. Input Bigg Current	$T_A = +25^{\circ}C$		-100		+100	nA	
FB_ Input Bias Current	$T_A = +85^{\circ}C$			-8			
DRV_ Soft-Start Charging Current				100		μΑ	
DDV May Sourcing Current	V <sub>FB</sub> _ = 0.45V	$T_A = 0$ °C to +85°C	4			mA	
DRV_ Max Sourcing Current		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	3	7			
DDV May Sinking Current	V== 0.6V	$T_A = 0$ °C to +85°C	3			mA	
DRV_ Max Sinking Current	$V_{FB} = 0.6V$ $T_{A} = -40^{\circ}C \text{ to } +30^{\circ}C$		1.8	7		IIIA	
DRV_ Max Voltage	$V_{DD} = 5V, V_{FB} = 0.46V$		4.7			V	
Dhv_ Max voltage	$V_{DD} = 13.2V, V_{FB} = 0.46V$		8.0		10.9	V	
FB_ Slow Short-Circuit Threshold	Measured at FB_	(falling)		400		mV	
FB_ Fast Short-Circuit Threshold	Measured at FB_	(falling)		300		mV	
Slow Short-Circuit Timer				50		μs	
FB_ to DRV_ Transconductance			0.115	0.24	0.460	Mho	
LOGIC							
EN_ Input Low Level					0.7	V	
EN_ Input High Level			1.3			V	
EN_ Input Leakage Current	$V_{EN_{-}} = 0$ and $V_{D}$	$T_A = +25^{\circ}C$	-0.1		+0.1	Δ	
Liv_ input Leanage Guirent	$V_{DD} = 13.2V$	$T_A = +85^{\circ}C$		0.001		μΑ	

#### **ELECTRICAL CHARACTERISTICS (continued)**

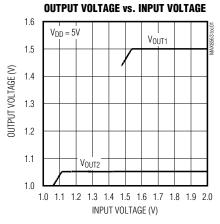
 $(V_{DD} = V_{EN1} = V_{EN2} = V_{EN3} = 5V, V_{GND} = 0V, T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 1)

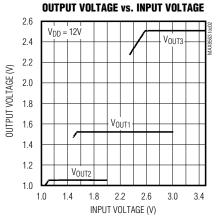
PARAMETER	CONDITI	CONDITIONS		TYP	MAX	UNITS
POK_ Threshold Falling	Measured at FB_ (falling)	Measured at FB_ (falling)		440	455	mV
POK_ Threshold Rising at Startup	Measured at FB_ (rising)	Measured at FB_ (rising)			485	mV
POK_ Output Low Level	Sinking 1mA, V <sub>DD</sub> = 4.5\	Sinking 1mA, V <sub>DD</sub> = 4.5V, V <sub>FB</sub> = 0.4V			0.1	V
DOM Output High Lookers	\/	T <sub>A</sub> = +25°C			0.1	
POK_ Output High Leakage	$V_{DD} = 5.5V$	$T_A = +85^{\circ}C$		0.001		μΑ

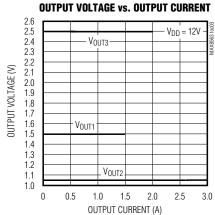
**Note 1:** Specifications are production tested at  $T_A = +25$ °C. Maximum and minimum specifications over temperature are guaranteed by design.

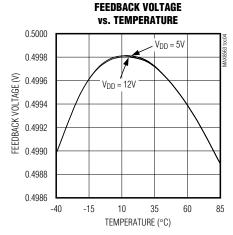
### Typical Operating Characteristics

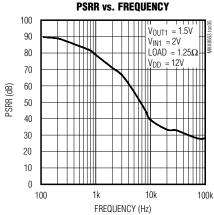
(Circuit of Figure 1,  $T_A = +25$ °C.)

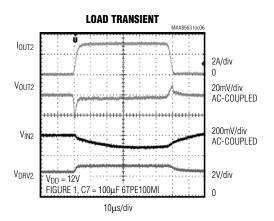






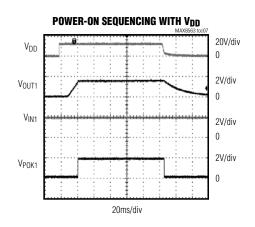


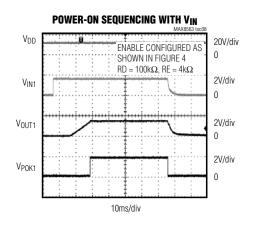


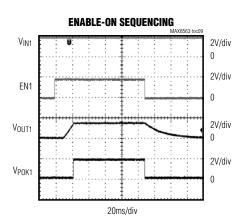


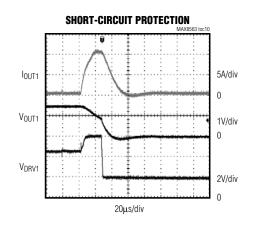
Typical Operating Characteristics (continued)

(Circuit of Figure 1,  $T_A = +25$ °C.)

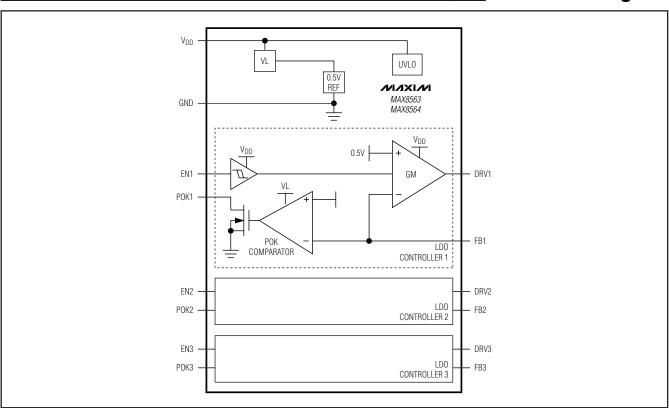








### **Functional Diagram**



### Pin Description

PIN	NAME		FUNCTION			
PIN	MAX8563 MAX8564					
1	DRV1	DRV1	Output n-MOSFET Drive. Drives the gate of an external n-channel MOSFET to regulate output 1. DRV1 is internally pulled to ground when EN1 is logic low. Connect an external series RC circuit for compensation. See the <i>Stability Compensation</i> section.			
2	FB1	FB1	Feedback Input for Output 1. Connect to the center of a resistor-divider between output 1 and GND to set the output voltage of output 1. The feedback regulation voltage is 0.500V. See the <i>Output Voltage Setting</i> section.			
3	EN1	EN1	Enable Control for Output 1. Drive logic high to enable output 1, or logic low to disable the output. Connect to V <sub>DD</sub> for always-on operation.			
4	POK1	POK1	Output 1 Power-Good Signal. Open-drain output pulls low when output 1 is 12% below the nominal regulated voltage.			
5	GND	GND	Ground			
6	_	POK2	Output 2 Power-Good Signal. Open-drain output pulls low when output 2 is 12% below the nominal regulated voltage.			
	N.C.	_	No Internal Connection			

### Pin Description (continued)

BINI	NAME		FULLOTION				
PIN	MAX8563	MAX8564	FUNCTION				
	_	EN2	Enable Control for Output 2. Drive logic high to enable output 2, or logic low to disable the output. Connect to V <sub>DD</sub> for always-on operation.				
7	DRV3	_	Output 3 n-MOSFET Drive. Drives the gate of an external n-channel MOSFET to regulate output 3. DRV3 is internally pulled to ground when EN3 is logic low. Connect an external series RC circuit for compensation. See the <i>Stability Compensation</i> section.				
8	_	FB2	Feedback Input for Output 2. Connect to the center of a resistor-divider between output 2 and GND to set the output voltage of output 2. The feedback regulation voltage is 0.500V. See the Output Voltage Setting section.				
0	FB3	_	Feedback Input for Output 3. Connect to the center of a resistor-divider between output 3 and GND to set the output voltage of output 3. The feedback regulation voltage is 0.500V. See the <i>Output Voltage Setting</i> section.				
9	— DRV2		Output 2 n-MOSFET Drive. Drives the gate of the external n-channel MOSFET to regulate output 2. DRV2 is internally pulled to ground when EN2 is logic low. Connect an external series RC circuit for compensation. See the <i>Stability Compensation</i> section.				
	EN3	_	Enable Control for Output 3. Drive logic high to enable output 3, or logic low to disable the output. Connect to V <sub>DD</sub> for always-on operation.				
10	- V <sub>DD</sub> - POK3 -		+5V or +12 Supply Input. Connect to external +5V or +12V supply rail. Bypass with a 0.1µF ceramic or larger capacitor.				
10			Output 3 Power-Good Signal. Open-drain output pulls low when output 3 is 12% below the nominal regulated voltage.				
11	N.C.	_	No Internal Connection				
12	POK2		Output 2 Power-Good Signal. Open-drain output pulls low when output 2 is 12% below the nominal regulated voltage.				
13	EN2	_	Enable Control for Output 2. Drive logic high to enable output 2, or logic low to disable the output. Connect to a V <sub>DD</sub> for always-on operation.				
14	FB2	_	Feedback Input for Output 2. Connect to the center of a resistor-divider between output 2 and GND to set the output voltage of output 2. The feedback regulation voltage is 0.500V. See the Output Voltage Setting section.				
15	DRV2	_	Output 2 n-MOSFET Drive. Drives the gate of the external n-channel MOSFET to regulate output 2. DRV2 is internally pulled to ground when EN2 is logic low. Connect an external series RC circuit for compensation. See the <i>Stability Compensation</i> section.				
16	V <sub>DD</sub>	_	+5V or +12V Supply Input. Connect to an external +5V or +12V supply rail. Bypass with a 0.1µF ceramic or larger capacitor.				

### **Typical Application Circuits**

MAX8563: Triple Output

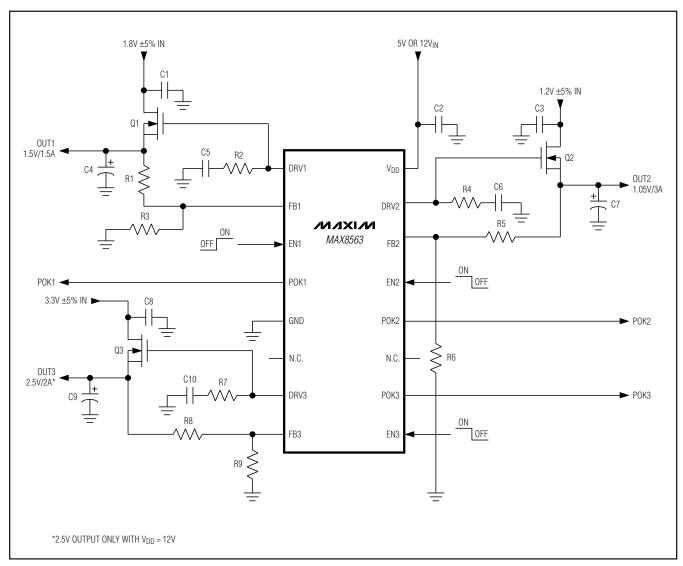


Figure 1. MAX8563 Typical Application Circuit

### Typical Application Circuits (continued)

MAX8564: Dual Output

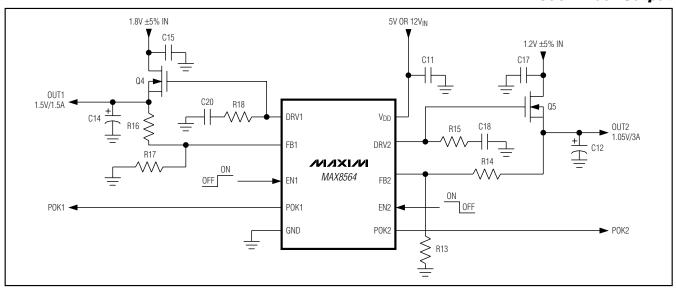


Figure 2. MAX8564 Typical Application Circuit

#### **MAX8563 External Component List**

• • • • • • • • • • • • • • • • • • •						
COMPONENTS	QTY	DESCRIPTION				
C1, C3, C8	3	2.2 $\mu$ F, 10V X5R ceramic capacitors (optional 100 $\mu$ F, 18m $\Omega$ , 6.3V aluminum electrolytic, Sanyo GTPE100MI in parallel)				
C2	1	0.1µF, 16V X7R ceramic capacitor				
C4, C7, C9	3	100μF, 18mΩ, 6.3V aluminum electrolytic capacitors Sanyo GTPE100MI				
C5, C6, C10	3	1μF, 16V X7R ceramic capacitors				
Q1/Q2 (Dual)	1	Dual n-channel MOSFETs, 30V, $18m\Omega$ Vishay Si4922DY				
Q3	1	N-channel MOSFET, 30V, 50m $\Omega$ Fairchild Semiconductor FDD6630A				
R1	1	665Ω ±1% resistor				
R2	1	620Ω ±5% resistor				
R3	1	332Ω ±1% resistor				
R4	1	390Ω ±5% resistor				
R5	1	182Ω ±1% resistor				
R6	1	165Ω ±1% resistor				
R7 1		910Ω ±5% resistor				
R8 1		1kΩ ±1% resistor				
R9	1	249Ω ±1% resistor				

#### **MAX8564 External Component List**

COMPONENTS	QTY	DESCRIPTION
C11	1	0.1µF, 16V X7R ceramic capacitor
C12, C14	2	100μF, 18mΩ, 6.3V aluminum electrolytic capacitors Sanyo GTPE100MI
C15, C17	2	2.2 $\mu$ F, 10V X5R ceramic capacitors (optional 100 $\mu$ F, 18m $\Omega$ , 6.3V aluminum electrolytic, Sanyo GTPE100MI in parallel)
C18, C20	2	1μF, 16V X7R ceramic capacitors
Q4/Q5 (Dual)	1	Dual n-channel MOSFETs, 30V, $18m\Omega$ Vishay Si4922DY
R13	1	165Ω ±1% resistor
R14	1	182Ω ±1% resistor
R15	1	390Ω ±5% resistor
R16	1	665Ω ±1% resistor
R17	1	332Ω ±1% resistor
R18	1	620Ω ±5% resistor

#### **Detailed Description**

The MAX8563/MAX8564 triple and dual LDO controllers allow flexible and inexpensive voltage conversion by controlling the gate of an external n-MOSFET in a source-follower configuration. The MAX8563/MAX8564 consist of multiple identical LDO controllers. Each LDO controller features an enable input (EN\_) and a power-OK output (POK\_). The MAX8563/MAX8564 also include a 0.5V reference, an internal regulator, and an undervoltage lockout (UVLO). The transconductance amplifier measures the feedback voltage on FB\_ and compares it to an internal 0.5V reference connected to the positive input. If the voltage on FB\_ is lower than 0.5V, the current output on the gate-drive output DVR\_ is increased. If the voltage on FB\_ is higher than 0.5V, the current output on the gate-drive output is decreased.

#### Bias Voltage (VDD), UVLO, and Soft-Start

The MAX8563/MAX8564 bias current for internal circuitry is supplied by VDD. The VDD voltage range is from 4.5V to 13.2V. If VDD drops below 3.76V (typ), the MAX8563/MAX8564 assume that the supply and reference voltages are too low and activate the UVLO circuitry. During UVLO, the internal regulator (VL) and the internal bandgap reference are forced off, DRV\_ is pulled to GND, and POK\_ is pulled low.

Before any internal startup circuitry is activated, V<sub>DD</sub> must be above the UVLO threshold. After UVLO indicates that V<sub>DD</sub> is high enough, the internal VL regulator, the internal bandgap reference, and the bias currents are activated. If EN\_ is logic-high after the internal reference and bias currents are activated, then the corresponding DRV\_ output initiates operation in soft-start mode. Once the voltage on FB\_ reaches 94% of the regulation threshold, the full output current of the LDO controller is permitted.

When an LDO is activated, the respective DRV\_ is pulled up from GND with a typical soft-start current of 100 $\mu$ A. The soft-start current limits the slew of the output voltage and also limits the initial spike of current that the drain of the external n-MOSFET receives. The size of the compensation capacitor (C<sub>C</sub>) limits the slew rate (see Figure 3). This slew rate is equal to (100 / C<sub>C</sub>)mV/ms, where C<sub>C</sub> is in  $\mu$ F. The maximum drain current during startup is the ratio of C<sub>OUT</sub> to C<sub>C</sub> multiplied by the soft-start current of 100 $\mu$ A.

## Input Voltage (Drain Voltage of the External n-MOSFET)

The minimum input voltage to the drain of the n-MOSFET is a function of the desired output voltage and the dropout voltage of the n-MOSFET. Details on calculating this value are covered in the *Power MOSFET Selection* section.

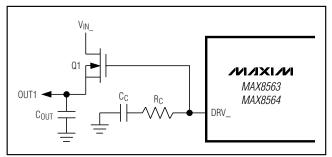


Figure 3. Soft-Start and Compensation Schematic

The maximum input voltage to the drain of the n-MOSFET is a function of the breakdown voltage and the thermal conditions during operation. The breakdown voltage from drain to source is normally provided in the MOSFET data sheet. The theoretical maximum input voltage is the set output voltage plus the breakdown voltage. The thermal constraint is usually the largest concern when discussing maximum input voltage. Details on calculating this value are covered in the Power MOSFET Selection section. The MOSFET package and thermal relief on the board are the largest contributors to removing heat from the n-MOSFET. Since output voltage is normally set and maximum output current is fixed, the input voltage becomes the only variable that determines the maximum power dissipated. Thus, the maximum input voltage is limited by the power capability of the n-MOSFET, if it is less than the breakdown voltage, which is most often the case. Ensure input capacitors handle the maximum input voltage.

During a power-up sequence where V<sub>DD</sub> and EN\_ rise before the input to the drain of the n-MOSFET, the MAX8563/MAX8564 drive DRV\_ high but the output does not rise. As DRV\_ rails and VFB\_ is still below 80% of the regulation voltage, the MAX8563/MAX8564 assume that an output short-circuit fault is present and shut down that regulator. To avoid this error condition, connect a resistor-divider from VDD to IN\_ with the middle node connected to the respective EN\_ (see Figure 4). Use the following equations to calculate the resistor values.

When V<sub>IN</sub> is off or at a low-voltage state:

$$0.7 > \left(\frac{R_E}{R_E + R_D}\right) \times \left(V_{DD} - V_{IN}\right) + V_{IN}$$

When V<sub>IN</sub> is on or at a high-voltage state:

$$1.3 \!<\! \left(\frac{R_E}{R_E \!+\! R_D}\right) \!\times \left(V_{DD} \!-\! V_{IN}_{\_}\right) \!+\! V_{IN}_{\_}$$

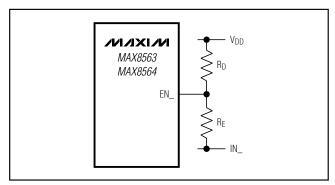


Figure 4. Voltage-Divider on EN\_

Set R<sub>D</sub> = 100k $\Omega$ . The above equations also assume that V<sub>DD</sub> > V<sub>IN</sub>\_ > 1V when V<sub>IN</sub>\_ is on or at a high-voltage state, and that V<sub>DD</sub> > 3V.

Example: Connect 100k $\Omega$  from EN to V<sub>DD</sub> and 4k $\Omega$  from EN\_ to IN\_. Thus, when V<sub>DD</sub> = 12V and V<sub>IN\_</sub> = 0V, then V<sub>EN\_</sub> = 0.46V. When V<sub>DD</sub> = 12V and V<sub>IN\_</sub> = 1.2V, then V<sub>EN\_</sub> = 1.6V.

Alternately, to avoid fault shutdown due to the delay of  $V_{\text{IN}}$  relative to  $V_{\text{DD}}$ , pull EN\_ low with a separate control logic and only drive high when  $V_{\text{IN}}$  reaches a steady-state value.

#### Output Voltage

The output voltage range at the source of the n-MOSFET is from 0.5V to 3.3V when V<sub>DD</sub> is 12V and from 0.5V to 1.8V when V<sub>DD</sub> is 5V. The maximum output voltage is a function of the minimum gate-to-source voltage (V<sub>GS</sub>) of the MOSFET and V<sub>DD</sub>.

The external n-MOSFET contains a parasitic diode from source to drain. If the output is ever anticipated to exceed the input, current flows from source to drain. If this is undesirable, external protection is needed. A simple solution is the placement of a diode in series, from IN\_ to the drain of the n-MOSFET, so that reverse current is not possible. Due to the forward-voltage drop of the diode, the maximum output voltage is reduced and additional power is consumed in the diode.

#### **Enable and POK**

The MAX8563/MAX8564 have independent enable control inputs (EN1, EN2, and EN3). Drive EN1 high to enable output 1. Drive EN2 high to enable output 2. Drive EN3 high to enable output 3. When EN\_ is driven low, the corresponding DRV\_ is internally pulled to GND and POK\_ is internally pulled low.

The POK\_ is an open-drain output that provides the status of the output voltage and pulls low depending upon circuit conditions. During startup, once the FB\_ reaches the POK\_ threshold, the POK\_ signal goes high. The POK\_ threshold has 30mV of hysteresis. When the output voltage drops 12% below the nominal regulated voltage, POK\_ pulls low. All POK\_ outputs pull low when UVLO is activated or when the internal VL regulator and reference are not ready.

#### Output Undervoltage and Overload Protection

When an overload event or short circuit occurs, the device that is most vulnerable is the external n-MOSFET. The MAX8563/MAX8564 monitor the output voltage to protect the MOSFET. When DRV\_ is at its maximum voltage and the output voltage drops below 80% but is still greater than 60% of its nominal voltage for more than 50µs, the MAX8563/MAX8564 shut down that particular regulator output by pulling DRV\_ to GND. Note that there is an additional inherent delay in turning off the MOSFET. The delay is a function of the compensation capacitor and the MOSFET. If the output recovers to greater than 80% within 50µs, it is not considered to be in overload and no action is taken. When the output voltage drops below 60% of its nominal voltage, the MAX8563/ MAX8564 immediately shut down that particular regulator output by pulling DRV to GND. To restart that particular LDO. Vnn must be recycled below the UVLO or the corresponding EN\_ must be recycled. The overload protection is shown in the Typical Operating Characteristics.

#### Design Procedure

#### **Output Voltage Setting**

The minimum output voltage for each controller of the MAX8563/MAX8564 is typically 0.5V. The maximum output voltage is adjustable up to 3.3V with V<sub>DD</sub> = 12V, and up to 1.8V with V<sub>DD</sub> = 5V. To set the output voltage, connect the FB\_ pin to the center of a voltage-divider between OUT\_ and GND (Figure 5). The resistor-divider current should be at least 1mA per 1A of maximum output current; i.e., for a 3A maximum output current, set the resistor-divider bias current to ≥3mA.

$$I_{OUT(MIN)} \ge \frac{I_{OUT(MAX)}}{1000}$$
 $R_B \le \frac{V_{FB}}{I_{OUT(MIN)}} = 1000 \times \frac{V_{FB}}{I_{OUT(MAX)}} = \frac{500}{I_{OUT(MAX)}}$ 

$$R_A = R_B \times \left[ \left( \frac{V_{OUT}}{V_{FB}} \right) - 1 \right] = R_B \times (2 \times V_{OUT} - 1)$$

To set the output voltage to 0.5V, disconnect RB from FB\_ and connect it to OUT\_; this change maintains the minimum load requirement on the output. In this case, RA can vary from  $1k\Omega$  to  $10k\Omega$ .

#### **Input and Output Capacitor Selection**

The input filter capacitor aids in providing low input impedance to the regulator and also reduces peak currents drawn from the power source during transient conditions. Use a minimum 2.2µF ceramic capacitor from IN\_ (drain of the external pass n-MOSFET) to GND (see Figures 1 and 2). If large line transients or load transients are expected, increase the input capacitance to help minimize output voltage changes.

The output filter capacitor and its equivalent series resistance (ESR) contribute to the stability of the regulator (see the *Stability Compensation* section) and affect the load-transient response. If large step loads (no load to full load) are expected, and a very fast response (less than a few microseconds) is required, use a  $100\mu F$ ,  $18m\Omega$  POSCAP for the output capacitor. If a larger capacitance is desired, keep the capacitance ESR product (COUT x RESR) in the  $1\mu s$  to  $5\mu s$  range.

If the application expects smaller load steps (less than 50% of full load), then use a 6.8µF ceramic capacitor or larger per ampere of maximum output current. This option reduces the size and cost of the regulator circuit. Note that some ceramic dielectrics exhibit large capacitance variation with temperature. Use X7R or X5R dielectrics to ensure sufficient capacitance at all operating temperatures. Tantalum and aluminum capacitors are not recommended.

#### **Power MOSFET Selection**

MAX8563/MAX8564 use an n-channel MOSFET as the series pass transistor instead of a p-channel MOSFET to reduce cost. The selected MOSFET must have a gate threshold voltage that meets the following criteria:

where  $V_{DD}$  is the controller bias voltage, and  $V_{GS\_MAX}$  is the maximum gate voltage required to yield the onresistance ( $R_{DS\_ON}$ ) specified by the manufacturer's data sheet.  $R_{DS\_ON}$  multiplied by the maximum output

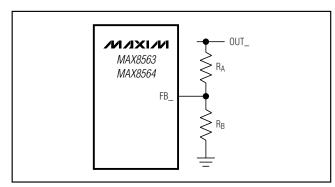


Figure 5. Adjustable Output Voltage

current (load current) is the maximum voltage dropout across the MOSFET, VDS\_MIN. Make sure that VDS\_MIN meets the condition below to avoid entering dropout, where output voltage starts to decrease and any ripple on the input also passes through to the output.

where V<sub>IN\_MIN</sub> is the minimum input voltage at the drain of the MOSFET. V<sub>DS\_MIN</sub> has a positive temperature coefficient; therefore, the value of V<sub>DS\_MIN</sub> at the highest operating junction temperature should be used.

For thermal management, the maximum power dissipation in the MOSFET is calculated by:

$$PD = (VIN\_MAX - VOUT) \times IOUT\_MAX$$

The MOSFET is typically in an SMT package. Refer to the MOSFET data sheet for the PC board area needed to meet the maximum operating junction temperature required.

#### **Stability Compensation**

Connect a resistor, RC, and a capacitor, CC, in series from the DRV\_ pin to GND. The values of the compensation network depend upon the external MOSFET characteristics, the output current range, and the programmed output voltage. The following parameters are needed from the MOSFET data sheet: the input capacitance (CISS at VDS = 1V), the typical forward transconductance (gFS) and the current at which gFS was measured (IDFS). Calculate the transconductance of the FET at the maximum load current (IOUT\_MAX):

$$g_{C(MAX)} = g_{FS} \times \sqrt{\frac{I_{OUT\_MAX}}{I_{DFS}}}$$

For the best transient response in applications with large step loads (see the *Input and Output Capacitor Selection* section for output capacitance requirements), use the following equations to select the compensation components:

$$C_{C} = \frac{\begin{bmatrix} 0.16 \times V_{OUT} \times C_{OUT} \times \\ g_{C(MAX)} \times (g_{C(MAX)} \times R_{ESR} + 1) \end{bmatrix}}{\left(g_{C(MAX)} \times V_{OUT} + I_{OUT\_MAX}\right)^{2}} - C_{ISS}$$

$$R_{C} = 59 \times \frac{V_{OUT} \times C_{OUT}(g_{C(MAX)} \times R_{ESR} + 1)}{C_{C} \times (g_{C(MAX)} \times V_{OUT} + I_{OUT\_MAX})}$$

where  $C_{\text{OUT}}$  is the output capacitance and  $R_{\text{ESR}}$  is the ESR of  $C_{\text{OUT}}$ .

To use a low-cost ceramic capacitor (see the *Input and Output Capacitor Selection* section for load-transient response characteristics), use the following equations to select the compensation components:

$$C_{C} = \frac{C_{OUT} \times g_{C(MAX)}}{\left(g_{C(MAX)} \times V_{OUT} + I_{OUT\_MAX}\right)} - C_{ISS}$$

$$R_{C} = 15 \times \frac{C_{OUT}}{C_{C} \times g_{C(MAX)}}$$

#### Example

OUTPUT 1 of Figure 1 is used in this example. Table 1 shows the values required to calculate the compensation. The values were taken from the appropriate data sheets and Figure 1.

Table 1. Parameters Required to Calculate Compensation

PARAMETER	CONDITIONS	VALUE	UNITS
MOSFET CISS	$V_{DS} = 1V$	2500	рF
MOSFET GFS	IDFS = 8.8A	30	S
V <sub>OUT1</sub>	Figure 1	1.5	V
IOUT_MAX	Figure 1	1.5	А
C <sub>OUT1</sub>	Figure 1	100	μF
RESR	Figure 1	18	mΩ

$$g_{C(MAX)} = 30S \times \sqrt{\frac{1.5A}{8.8A}} = 12.4S$$

$$C_{C} = 0.16 \times \frac{1.5V \times 100\mu F \times 12.4S \times \left(\frac{12.4S \times 18m\Omega + 1}{18m\Omega + 1}\right)}{\left(12.4S \times 1.5V + 1.5A\right)^{2}} - \frac{2500pF = 0.90\mu F, \text{ use } 1\mu F.}{1\mu F \left(12.4S \times 1.5V + 1.5A\right)}$$

$$R_{C} = 59 \times \frac{7.5V \times 100\mu F \times \left(12.4S \times 18m\Omega + 1\right)}{1\mu F \left(12.4S \times 1.5V + 1.5A\right)}$$

$$= 599.4\Omega, \text{ use } 620\Omega.$$

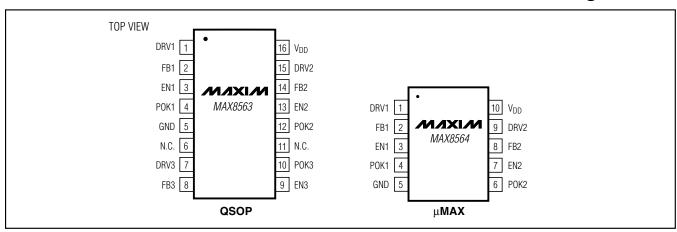
#### **PC Board Layout Guidelines**

Due to the high-current paths and tight output accuracy required by most applications, careful PC board layout is required. An evaluation kit (MAX8563EVKIT) is available to speed design.

It is important to keep all traces as short as possible to maximize the high-current trace dimensions to reduce the effect of undesirable parasitic inductance. The MOSFET dissipates a fair amount of heat due to the high currents involved, especially during large input-to-output voltage differences. To dissipate the heat generated by the MOSFET, make power traces very wide with a large amount of copper area. An efficient way to achieve good power dissipation on a surface-mount package is to lay out copper areas directly under the MOSFET package on multiple layers and connect the areas through vias. Use a ground plane to minimize impedance and inductance. In addition to the usual high-power considerations, here are four tips to ensure high output accuracy.

- Ensure that the feedback connection to C<sub>OUT</sub> is short and direct.
- Place the feedback resistors next to the FB pin.
- Place R<sub>C</sub> and C<sub>C</sub> next to the DRV\_pin.
- Ensure FB\_ and DRV\_ traces are away from noisy sources to ensure tight accuracy.

#### **Pin Configurations**



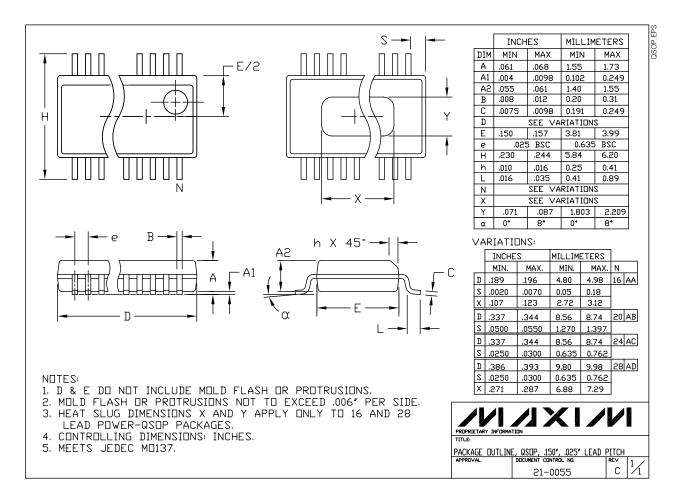
**Chip Information:** 

TRANSISTOR COUNT: 1801 PROCESS: BICMOS

MIXIM

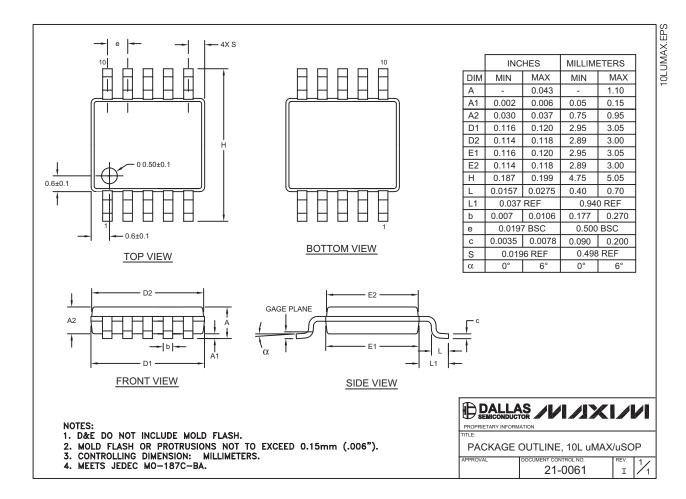
#### **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



#### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



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